Silicon Tracking for fSTAR

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Outline

Physics Motivation

Forward Tracking Requirements

Silicon-Based Forward Tracker

Summary

Forward Upgrade for pp/pA Physics

	Year	√s (GeV)	Delivered	Scientific Goals	Observable	Required
			Luminosity			Upgrade
	2017	p [†] p @ 510	400 pb ⁻¹	Sensitive to Sivers effect non-universality through TMDs	A_N for γ , W^{\pm} , Z^0 , DY	A _N ^{DY} : Postshower
			12 weeks	and Twist-3 $T_{q,F}(x,x)$		to FMS@STAR
				Sensitive to sea quark Sivers or ETQS function		
				Evolution in TMD and Twist-3 formalism		
				Transversity, Collins FF, linearly pol. Gluons,	$A_{UT}^{\sin(\phi_s-2\phi_h)} A_{UT}^{\sin(\phi_s-\phi_h)}$ modula-	None
				Gluon Sivers in Twist-3	tions of h^* in jets, $A_{UT}^{\sin{(\phi_S)}}$ for jets	
				First look at GPD Eg	A_{UT} for J/ Ψ in UPC	None
	2023	р ^т р @ 200	300 pb ⁻¹	subprocess driving the large A_N at high x_F and η	A_N for charged hadrons and flavor	Yes
S			8 weeks		enhanced jets	Forward instrum.
hec						
				evolution of ETQS fct.	A_N for γ	None
<u>=</u>				properties and nature of the diffractive exchange in	A_N for diffractive events	None
Scheduled RHIC		•	0	p+p collisions.		
	2023	p [†] Au @ 200	1.8	What is the nature of the initial state and hadronization in nuclear collisions	R_{phx} direct photons and DY	$R_{pAu}(DY)$:Yes
run ning				nuclear collisions		Forward instrum.
Ē.			72	Nuclear dependence of TMDs and nFF	$A_{UT}^{\sin(\phi_s-\phi_h)}$ modulations of h^* in	None
95					jets, nuclear FF	Tione
		\sim	ĺ		jets, nuclear FF	
		()V		Clear signatures for Saturation	Dihadrons, γ-jet, h-jet, diffraction	Yes
		0		<u> </u>		Forward instrum.
	2023	Al @ 200	12.6 pb ⁻¹	A-dependence of nPDF,	R_{pAl} : direct photons and DY	R _{pAl} (DY): Yes
1	\mathcal{A}		8 weeks	A-dependence of TMDs and nFF	rin(dds)	Forward instrum.
	/ -			A-dependence of TMDs and nrr	$A_{UT}^{\sin(\phi_s-\phi_h)}$ modulations of h^* in	None
					jets, nuclear FF	
(O)				A-dependence for Saturation	Dihadrons, γ-jet, h-jet, diffraction	Yes
					Dinaurons, 7-jet, n-jet, uniffaction	Forward instrum.
	202X	p [†] p@510	1.1 fb ⁻¹	TMDs at low and high x	A_{UT} for Collins observables, i.e.	Yes
Pot			10 weeks		hadron in jet modulations at $\eta > 1$	Forward instrum.
2 8				quantitative comparisons of the validity and the limits of	and	N
				factorization and universality in lepton-proton and proton-	mid-rapidity	None
in the				proton collisions	observables as in 2017 run	
Potential future running	202X	p p @ 510	1.1 fb ⁻¹	$\Delta g(x)$ at small x	/ A _{LL} for jets, di-jets, h/γ-jets	Yes
19			10 weeks		at $\eta > 1$	Forward instrum.
	T-1-1-1-2	. C	- C-11 OCD -	bysics program proposed in the years 2017 and 2023 and if an	13'6'1500 C-W131	11-

Table 1-2: Summary of the Cold QCD physics program propsed in the years 2017 and 2023 and if an additional 500 GeV run would become possible.

Forward Upgrade for AA Physics

Phy Measureme		Longitudinal de-correlation $C_n(\Delta \eta)$ $r_n(\eta_w \eta_b)$	η/s(T), ζ/s(T)	Mixed flow Harmonics $C_{m,n,m+n}$	Ridge	Event Shape
Detectors	Acceptance					and Jet- studies
Forward Calorimeter (FCS)	-2.5 > η > - 4.2 E _T (photons, hadrons)	One of these		One of these detectors necessary	Good to have	One of these detectors needed
Forward Tracking System (FTS)	-2.5 > η > - 4.2 (charged particles)	detectors necessary	Important		Important	

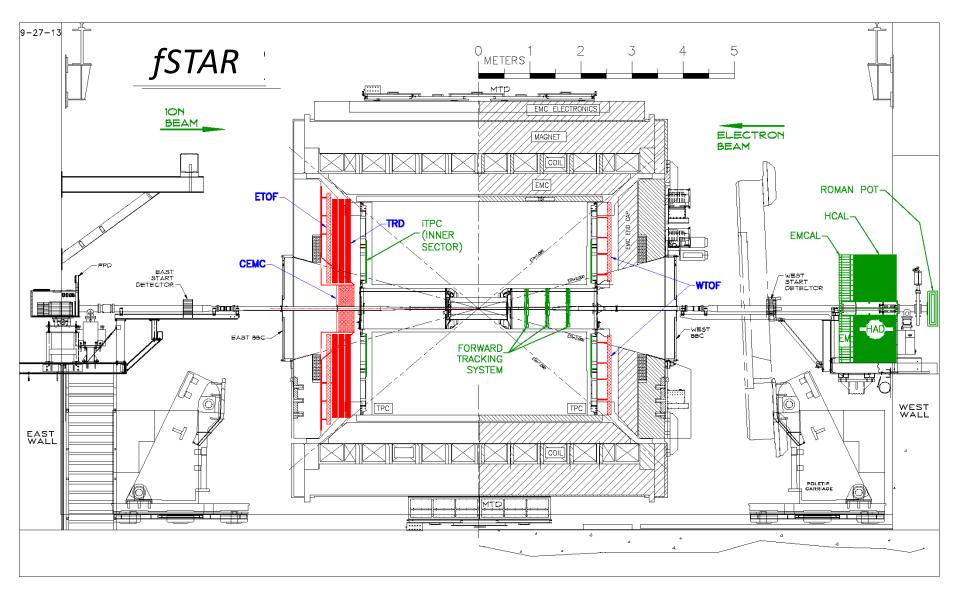
Table 2-1: Physics measurements in A+A collisions with the proposed forward upgrade and with other STAR upgrades that are relevant to those measurements.

Forward Tracking Requirements

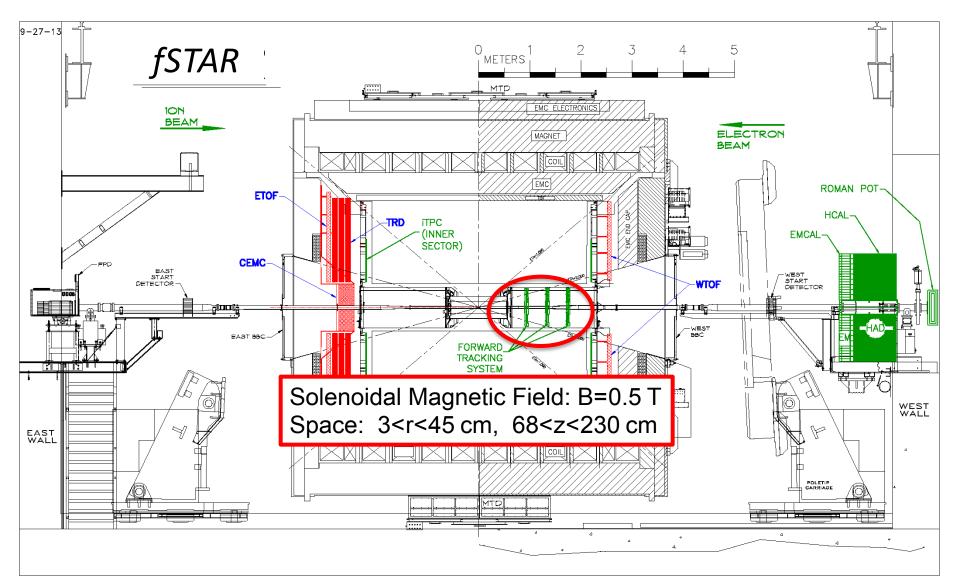
- pp/pA physics forward
 - charge separation for π⁺/π⁻, di-hadron, Drell-Yan (q)
 - → low mass, good φ resolution
 - e/h discrimination for Drell-Yan (p/E)
 - → good φ resolution
 - e/γ discrimination for direct photon, Drell-Yan (hit veto)
 - → low mass, high efficiency
 - Reconstruction of jets (p)
 - large η coverage, good φ resolution
- AA physics forward
 - Longitudinal fluctuation/even-shape engineering (p)
 - → low occupancy, good φ resolution, large η coverage
 - Long range correlation (p)
 - → low occupancy, good φ resolution, large η coverage

Good φ resolution
Large η coverage
High efficiency
Low occupancy
Low mass
Low cost

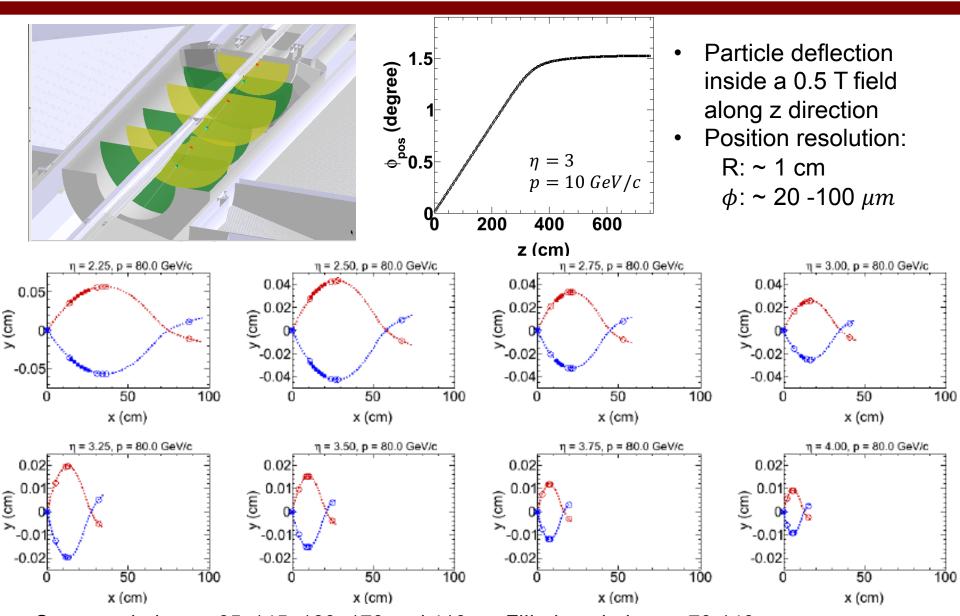
Location & Space Constraints



Location & Space Constraints

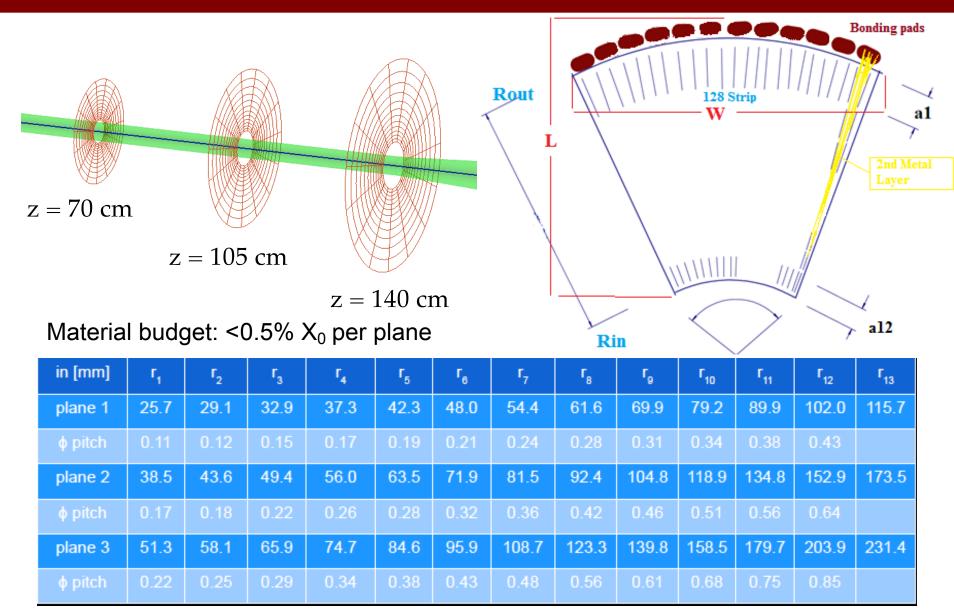


Particle Deflection in Magnetic Field

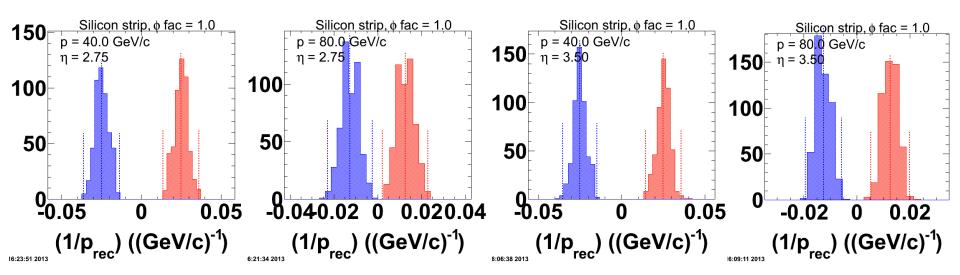


Open symbols: z = 65, 145, 160, 170 and 410 cm Filled symbols: z = 70-140 cm

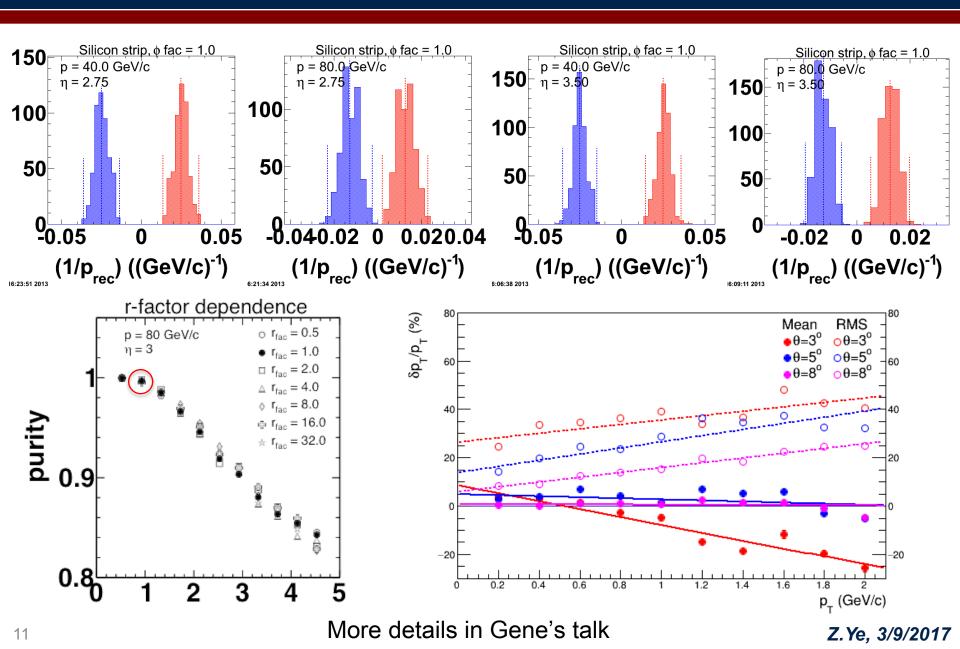
Layout with uniform width in η



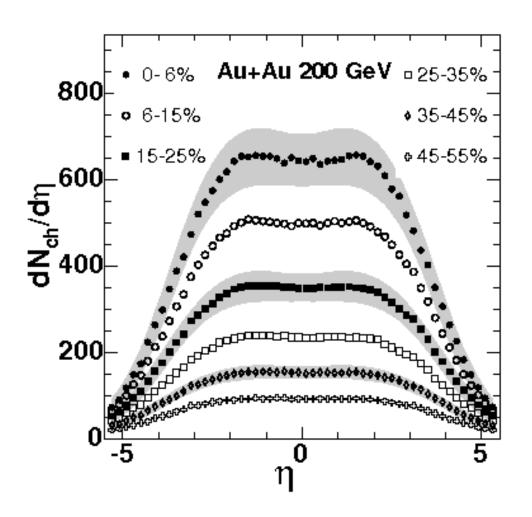
Performance from Simulation



Performance from Simulation



Occupancy

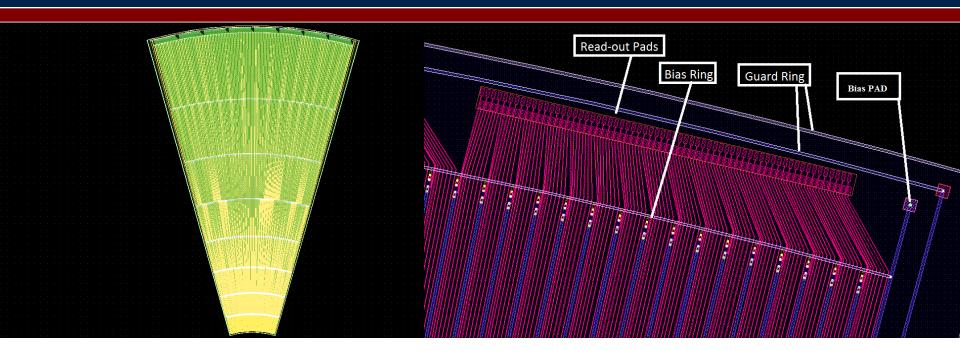


Assume total track=2*primary tracks:

Occupancy ≤ 5% (inner R) 10% (outer R)

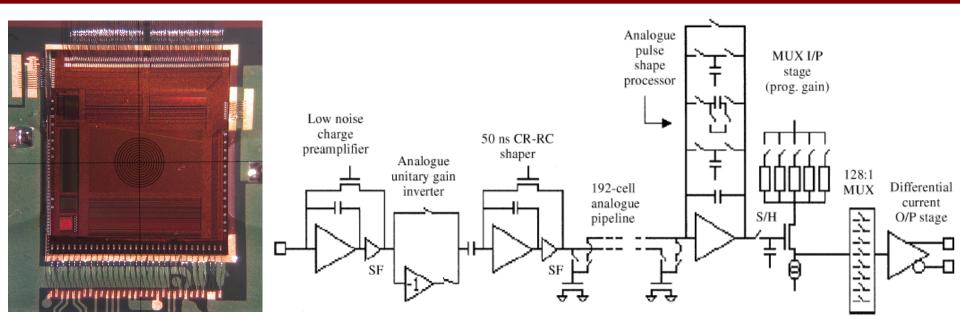
in 0-3% Au+Au collisions at 200 GeV

Silicon Sensors



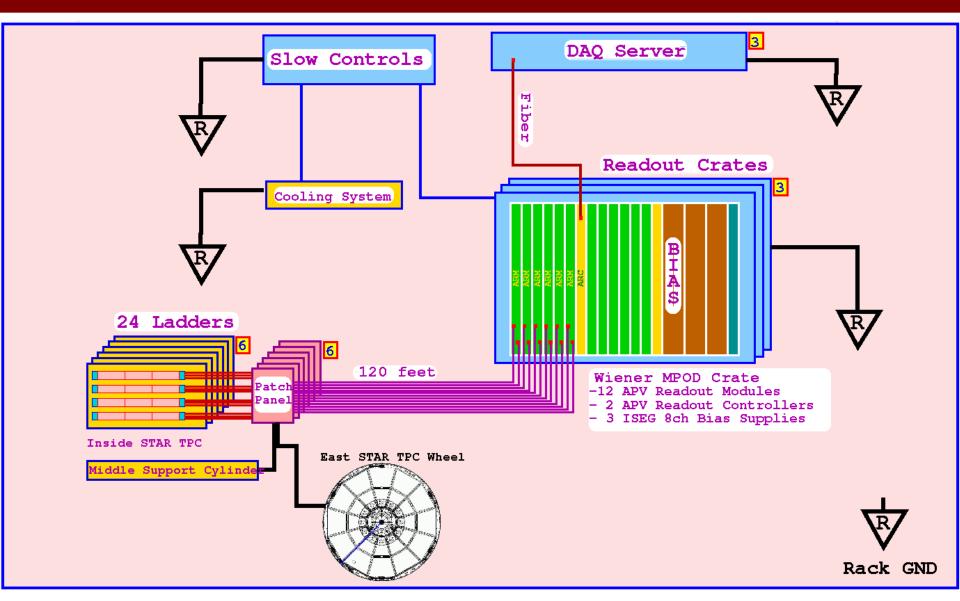
- Single-sided double-metal silicon ministrip sensors
- 8x128 strips per sensor, read out from the outer radius
- R&D needed to validate and optimize sensor design

Front-end Readout ASIC - APV25

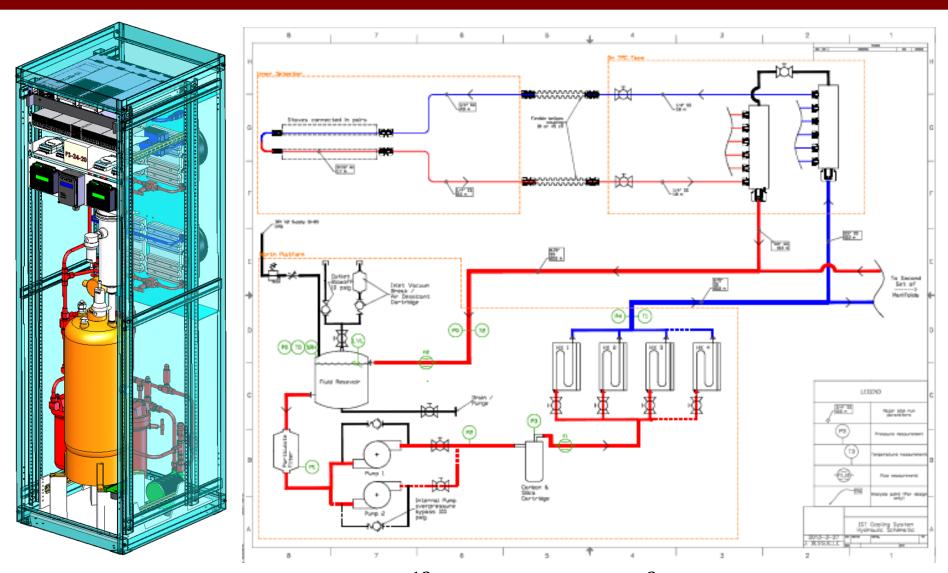


- 128 channels per chip, used successfully for STAR IST
- 1200 probe-tested chips in hand
- No R&D needed

DAQ System



Cooling System



Non-ionization radiation: $< 1 \times 10^{13} [1 \, MeV \, neutron/cm^2]$ Can use IST cooling system with liquid cooling in room temperature

Cost Estimation

Labor and contingency included:

WBS	WBS Description	Base Cost	Contingency	
Number	FTS (6-disk)			
y.1.1	Electronics	\$1,100,000	\$330,000 (30%)	
y.1.2	Mechanics	\$1,100,000	\$495,000 (45%)	
y.1.3	Assembly and Testing	\$560,000	\$196,000 (35%)	
y.1.4	Integration	\$450,000	\$225,000 (50%)	
Base Cost		\$3,210,000		
Contingency		\$1,246,000		
Total Cost		\$4,456,000 → \$4,036,000 *		

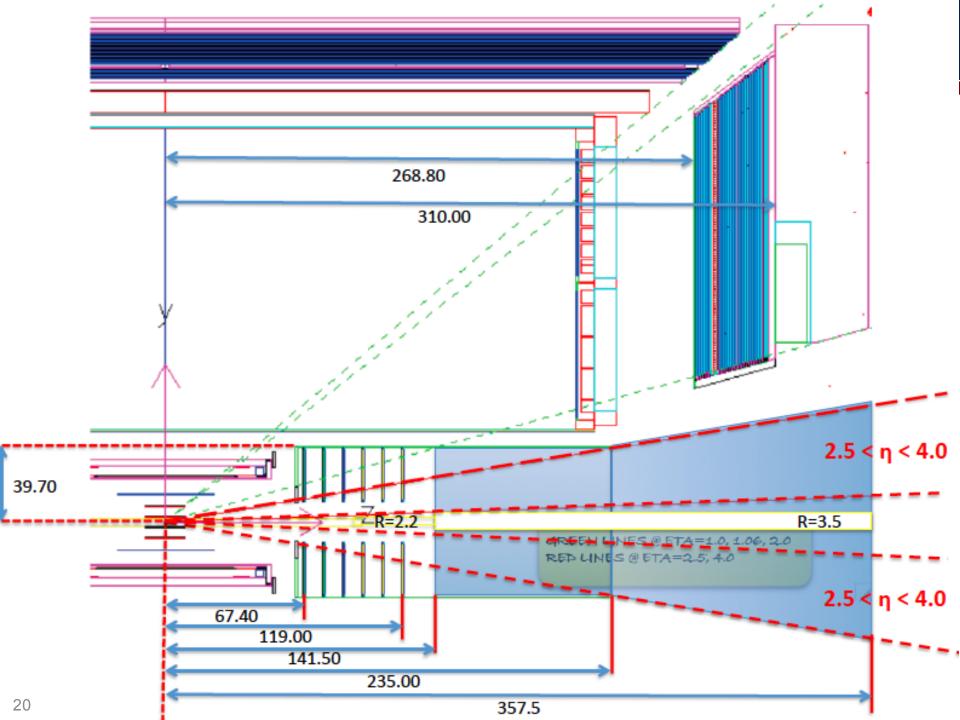
WBS	WBS Description	Base Cost	Contingency	
Number	FTS (3-disk)			
y.1.1	Electronics	\$700,000	\$210,000 (30%)	
y.1.2	Mechanics	\$740,000	\$333,000 (45%)	
y.1.3	Assembly and Testing	\$400,000	\$140,000 (35%)	
y.1.4	Integration	\$450,000	\$225,000 (50%)	
Base Cost		\$2,290,000		
Contingend	у	\$908,000		
Total Cost		\$3,198,000	→ \$2,898,000 *	

^{*} Cost if re-using IST DAQ and cooling systems

Summary

- A Silicon-based detector can satisfy the needed forward tracking requirements for pp/pA and AA physics programs
- A cost-effective path using APV25 for readout
 - Reuse the existing IST DAQ and cooling
 - Mechanical engineering needed for supporting structure
 - R&D needed for sensor design validation and optimization
- Other option under exploration
 - CBM STS (space, radiation, schedule)

Backup





Requirements (2)



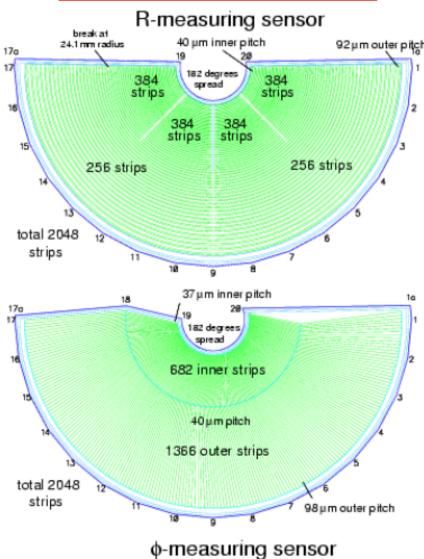
Trigger (see talk by Niels Tuning)

- FAST 2D (rz) and 3D (rzφ)
 standalone tracking for L1 Trigger:
 Choose RΦ geometry!
- Rejection of multiple interactions

Baseline Sensor Design

- •Sensors: 7mm>R>44mm (Active area 8mm to 43mm)
 - •182° angular coverage
 - R sensors
 - Pitch 40μm to 92μm
 - 45° inner, 90° outer sections
 - - Pitch 37μm to 40μm and 40μm to 98μm
 - Double stereo angle

LHCb VELO Detector





Requirements (2)



Trigger (see talk by Niels Tuning)

FAST 2D (rz) and 3D (rzφ)

LHCb VELO Detector

R-measuring sensor

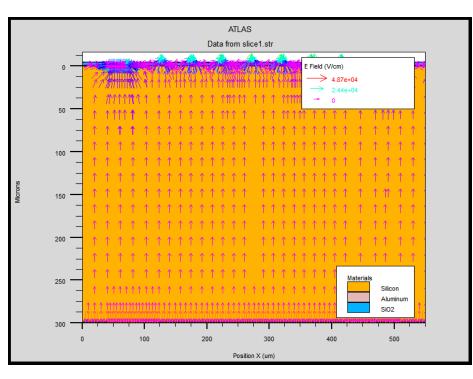
40 µm inner pitch 92 µm outer pitch 24.1 mm radius

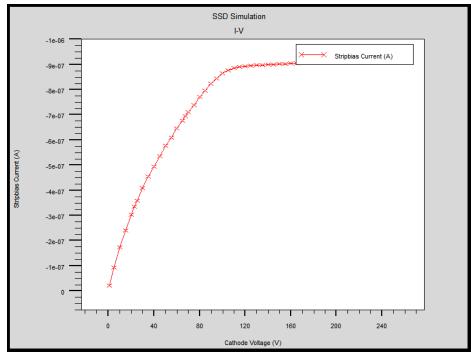
break at

98μm

Double stereo angle

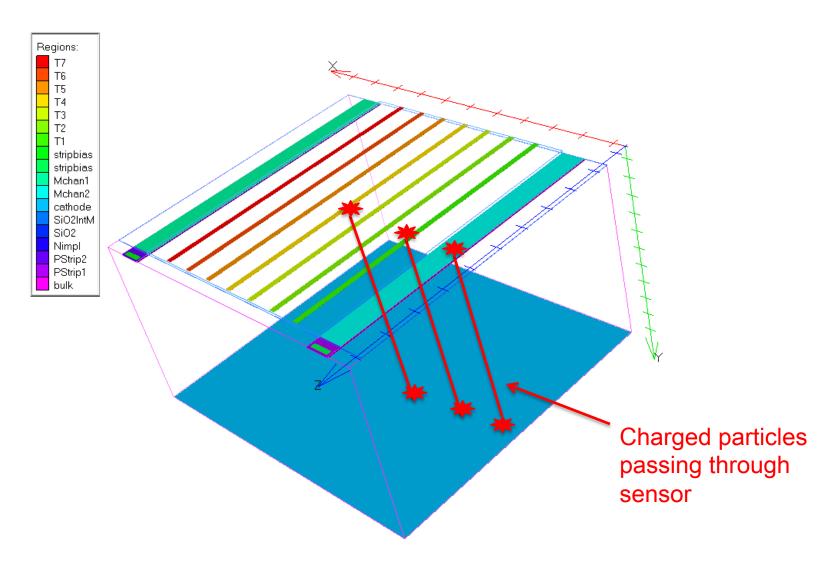
Sensor Simulation



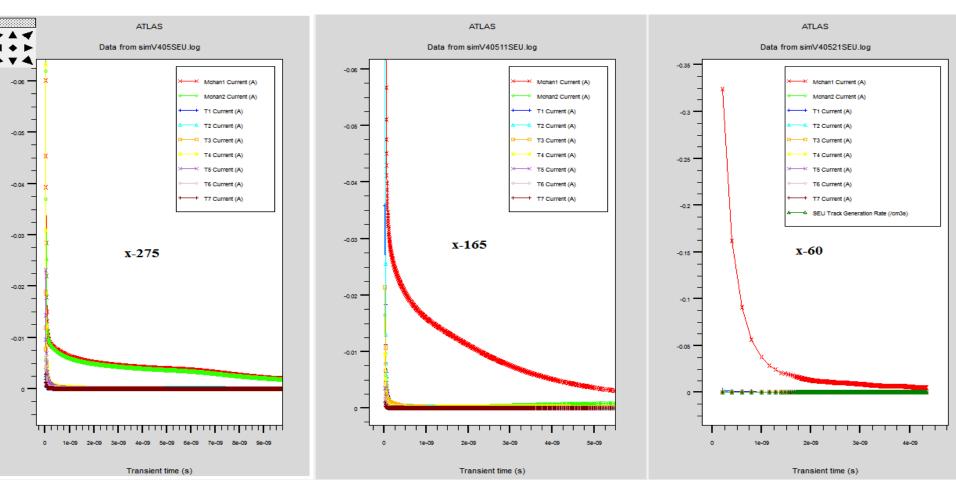


Good DC behavior, full depletion voltage ~ 100 V

Sensor Simulation



Sensor Simulation



Good signal behavior with small amount of cross-talk

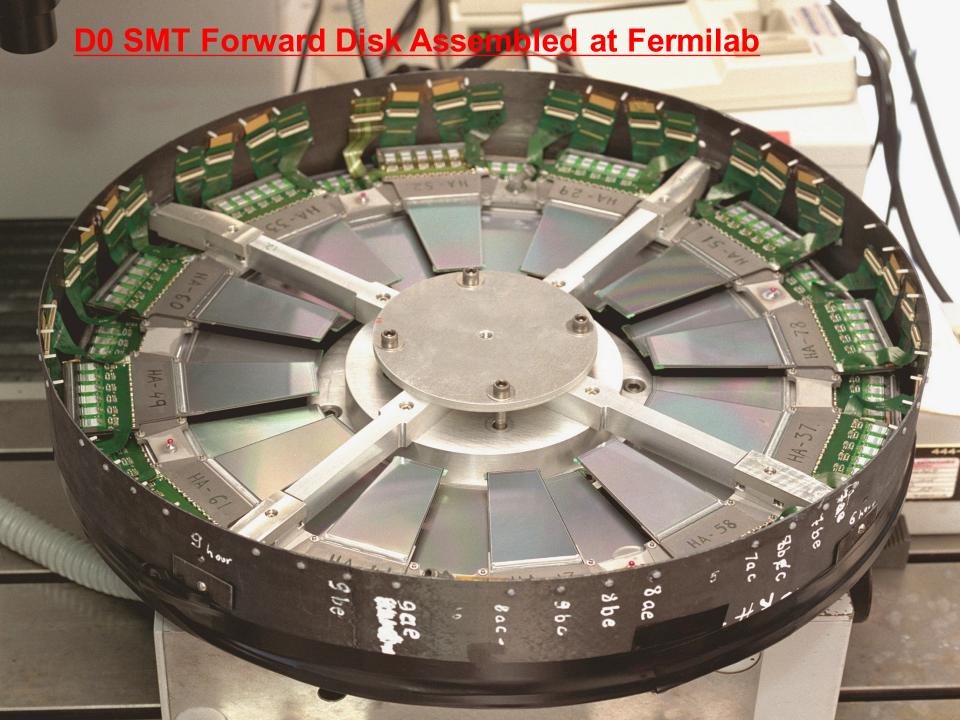
Silicon Sensor R&D

Schedule

- Finalize sensor wafer layout and place order Winter 2017
- Sensor QA test Spring 2018
- Prototype assembly ~ Summer 2018
- Prototype full performance test ~ Fall 2018

Deliverable

- Proof-of-principle and optimized sensor design
- Full detector system design by the end of year 2018

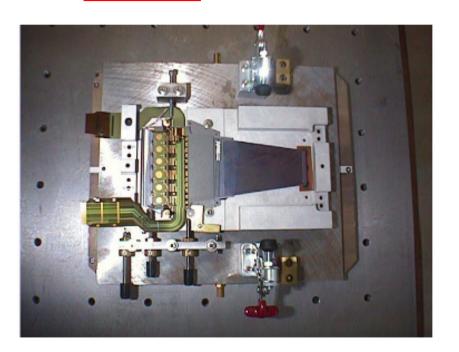


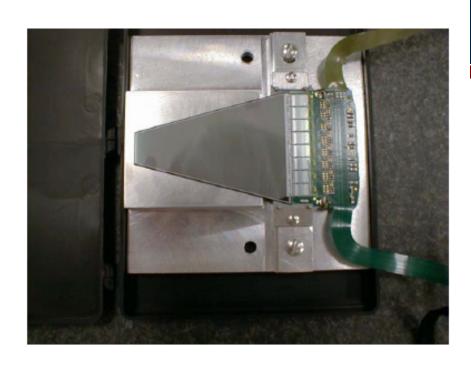
Disk Detectors

F-Wedge Detectors (144)

- *8+6 chip readout
- •2.6 cm < r < 10 cm
- Double sided wedges with ±15°
- •50 μ m (p-side), 62.5 μ m (n-side)
- Variable strip length







H-Wedge Detectors (384)

- •6+6 chip readout
- •9.6 cm < r < 23.6 cm
- •Single sided glued back-to-back with ±7.50
- •40 μm (p-side) strip pitch
- *80 µm readout pitch
- Variable strip length

